

Term 7- Sept 2025

Nanoelectronics and Technology  
(01.119/99.503)-Week 1 Class 2

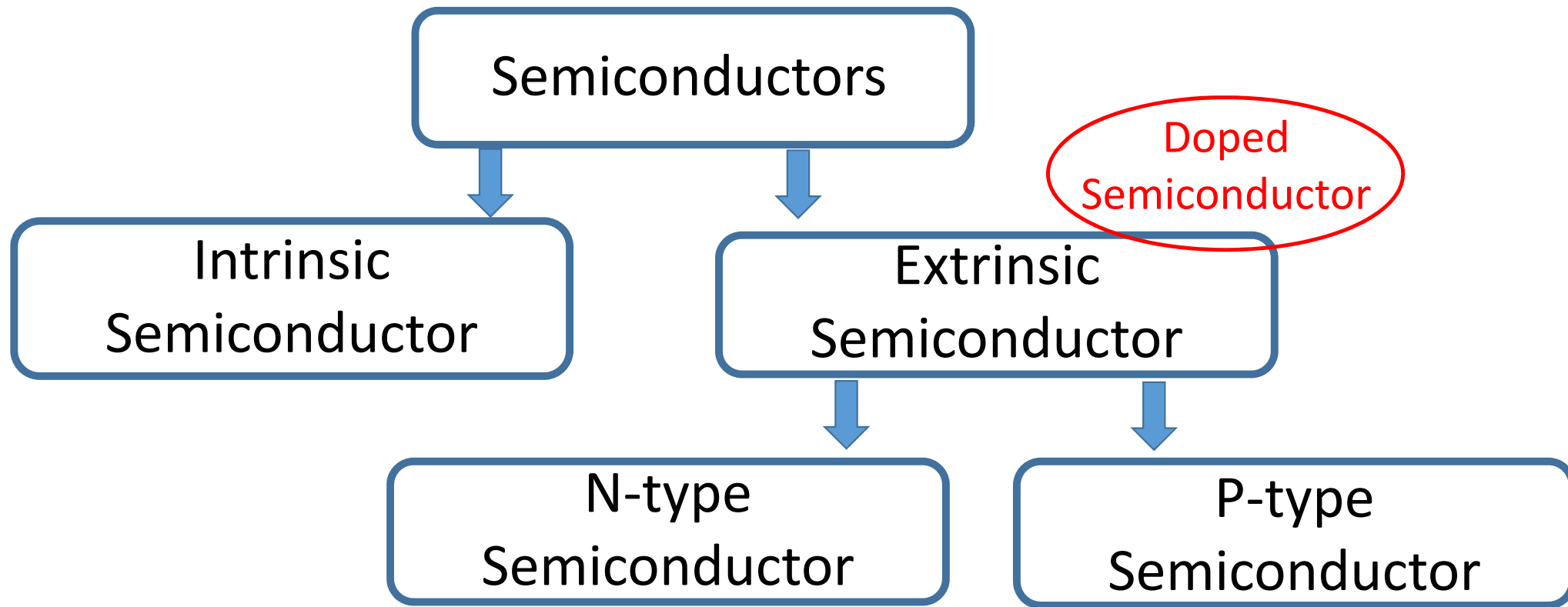
Shubhakar K  
18-Sept- 2025

Email: [shubhakar@sutd.edu.sg](mailto:shubhakar@sutd.edu.sg)  
Office location: 1.602-26

# Outline

- Review of semiconductors- Silicon
- Carrier transport
- PN junction-Diodes
- Schottky Diodes
- Ohmic contact
- Introduction to MOS structure

# Review of Semiconductors



# Semiconductor Materials

- **Conductors**

- Gold
- Silver
- Copper
- Aluminum
- Cobalt

- **Semiconductors**

- Germanium
- Silicon
- Gallium Arsenide
- Carbon
- SiC
- GaN

- **Non-Conductors**

- Glass (3.8k)
- Air (1k)
- Silicon Dioxide (3.9k)
- Silicon Nitride (7.5k)
- Hafnium Dioxide (30k)

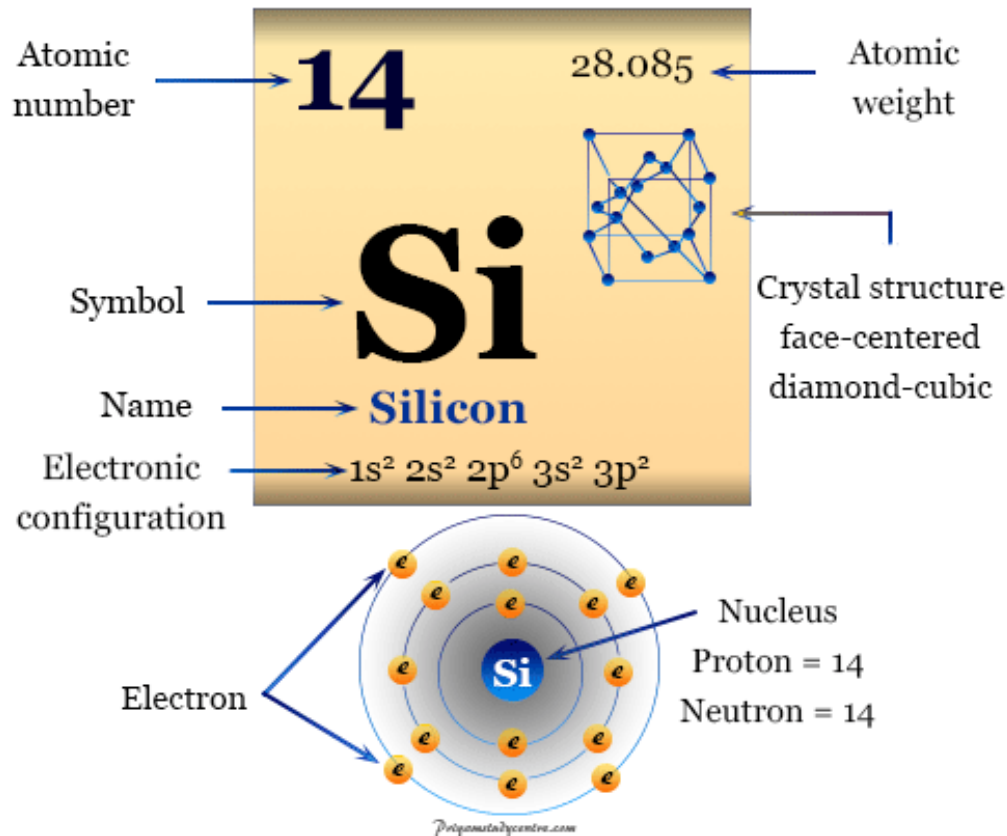
A **dielectric material** is a substance

that is a poor conductor of electricity, but an efficient supporter of electrostatic fields.

The **dielectric constant**, the extent to which a substance concentrates the electrostatic lines of flux

A **low-k** dielectric has a value of 3.9 or lower and a **high-k** a value of 4 or higher

# Silicon Semiconductor

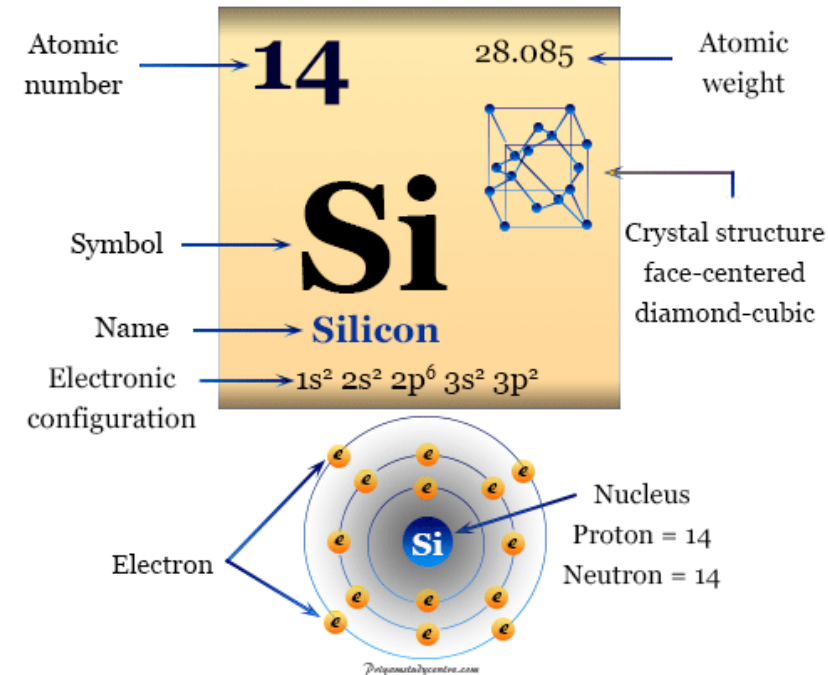


Silicon is used for integrated circuits (ICs) because its properties as a semiconductor, such as

- a stable, optimal bandgap and excellent thermal stability, allow for reliable and complex electronic components.
- Its mechanical strength, abundance and cost-effectiveness make it ideal for mass production and integration into a wide range of electronic devices.

# Silicon Semiconductor

- Si is a group 4 element, atomic no. 14 (14 protons & 14 electrons).
- 14 electrons in three shells config: 2 ) 8 ) 4 [orbital:  $1s^2 2s^2 2p^6 3s^2 3p^2$ ].
- There are 4 electrons in the outer "bonding" shell (**valence electrons**).
- Si atom shares the valence electrons to form strong covalent bonds with 4 neighbors, forming a tetrahedral structure (pyramid).



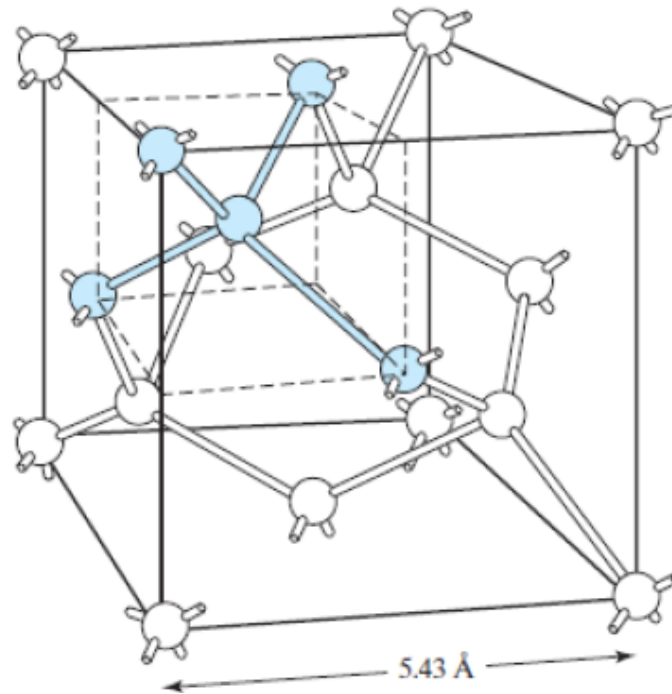
# Silicon Semiconductor

Lattice constant  $a = 5.431 \text{ \AA}$ .

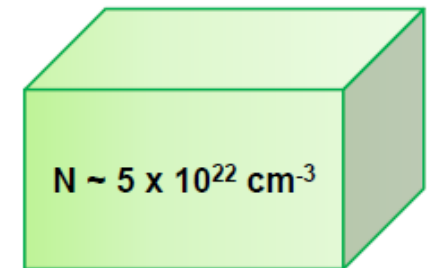
Si atomic density is

## *Silicon Crystal Structure*

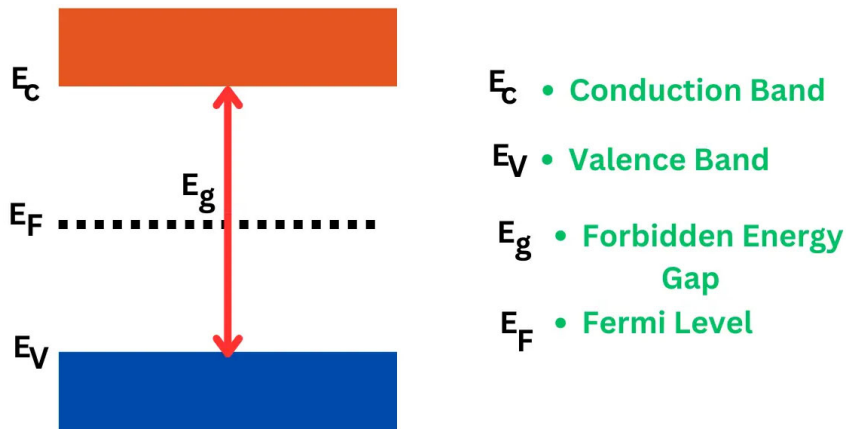
- *Unit cell* of silicon crystal is cubic.
- *Each Si atom has 4 nearest neighbors.*



$$\frac{8}{(5.431 \text{ \AA})^3} \approx 5 \times 10^{22} \text{ cm}^{-3}$$



# Silicon Semiconductor- Energy band



$E_G$	$T=300K$
Si	1.12eV

- The conduction band is the higher energy level band. This band is partially filled with electrons known as free electrons, as they are able to move anywhere within the solid.
- These electrons are responsible for the flow of current.
- There exists an energy gap between the conduction band and the valence band, and this difference in energy is referred to as the forbidden energy gap which determines the nature of a solid.
- At a temperature of 300°K, silicon has a forbidden gap of 1.12 eV

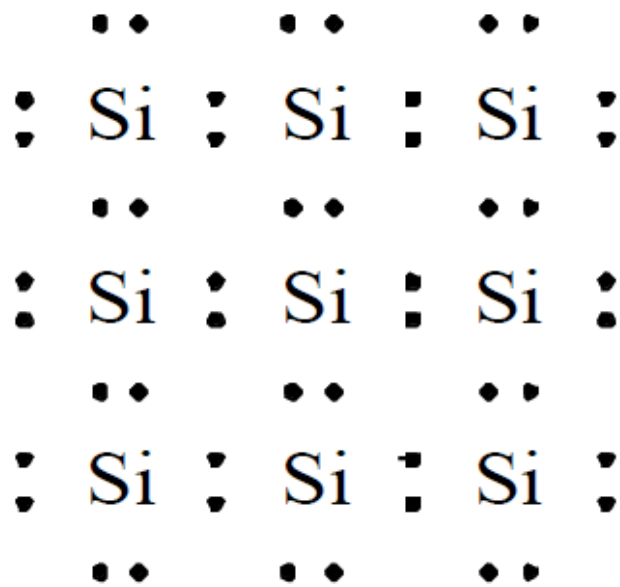
<https://www.electricalvolt.com/energy-bands-in-silicon/>



# Silicon Semiconductor- Intrinsic

Intrinsic silicon – pure, perfect without impurities in the crystal.

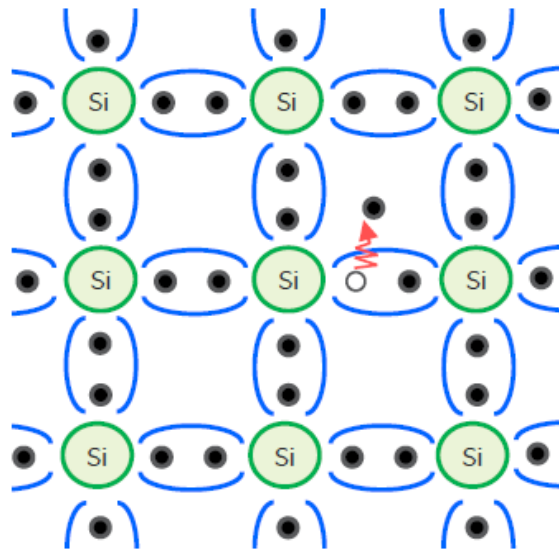
All bonds unbroken at  $T = 0$  K, free holes and electron concentration  $p_o = n_o = 0$ .



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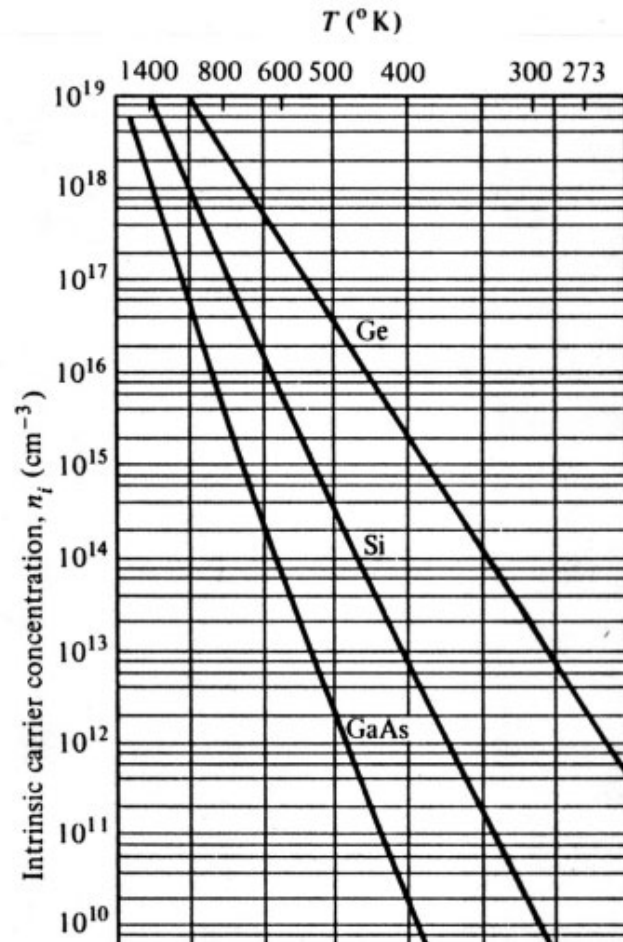
All bonds unbroken at  $T = 0$  K, free holes and electron concentration  $p_o = n_o = 0$ .



- Notice the temperature and bandgap dependency.  
At typical room temperature 300 K, Si  $n_i(T) \cong 10^{10} \text{ cm}^{-3}$ .

As  $T \uparrow$ , atoms vibrate which potentially break Si-Si bond and create a free electron and simultaneously it creates a vacant state (hole)  $\rightarrow n=p=n_i$ , measured in  $\# \text{ cm}^{-3}$

# Silicon Semiconductor- Intrinsic



Intrinsic carrier concentration is a material property that depends on temperature.

[https://sites.chemengr.ucsb.edu/~ceweb/courses/che142242/pdfs/lecture\\_3\\_chex42.pdf](https://sites.chemengr.ucsb.edu/~ceweb/courses/che142242/pdfs/lecture_3_chex42.pdf)

# Doping of Silicon Semiconductors-Extrinsic

## What is Doping?

- **Doping** is the intentional introduction of controlled impurities (dopant atoms) into pure silicon to tailor its electrical properties.
- Pure silicon is a **group IV element** with limited intrinsic conductivity. Adding small amounts of **group III (acceptors)** or **group V (donors)** elements changes the balance of charge carriers drastically.

Group V (donors)-N-type

		III	IV	V	VI
		B 5	C 6	N 7	O 8
		Al 13	Si 14	P 15	S 16
II	Zn 30	Ga 31	Ge 32	As 33	Se 34
	Cd 48	In 49	Sn 50	Sb 51	Te 52
	Hg 80	Tl 81	Pb 82	Bi 83	Po 84

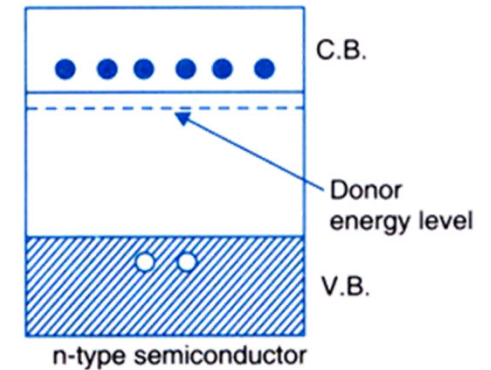
Group III (acceptors)-P-type

		III	IV	V	VI
		B 5	C 6	N 7	O 8
		Al 13	Si 14	P 15	S 16
II	Zn 30	Ga 31	Ge 32	As 33	Se 34
	Cd 48	In 49	Sn 50	Sb 51	Te 52
	Hg 80	Tl 81	Pb 82	Bi 83	Po 84

# Doping of Silicon Semiconductors

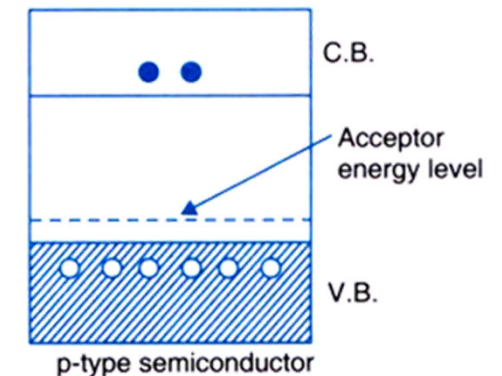
## (a) n-type Doping

- Dopant: **Group V elements** (e.g., Phosphorus, Arsenic, Antimony).
- Each dopant atom contributes an **extra electron** (donor electron).
- Majority carriers: **Electrons**
- Minority carriers: **Holes**
- Fermi level shifts **closer to the conduction band**.



## (b) p-type Doping

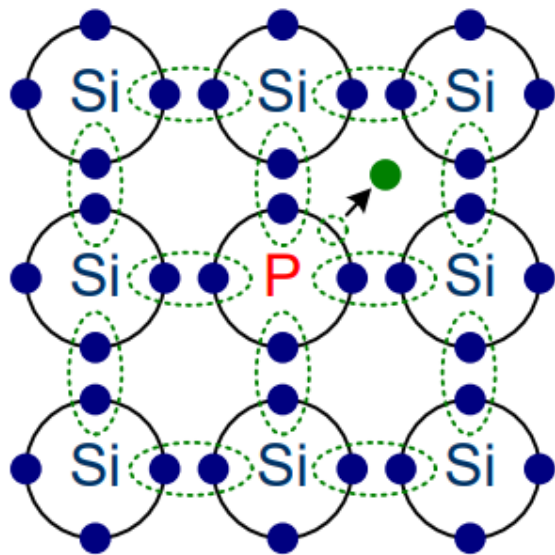
- Dopant: **Group III elements** (e.g., Boron, Gallium, Aluminum, Indium).
- Each dopant atom creates a **deficiency of an electron** → a **hole**.
- Majority carriers: **Holes**
- Minority carriers: **Electrons**
- Fermi level shifts **closer to the valence band**.



<https://www.wiredfaculty.com/question/UTBKVFJVVk9VRWd4TWpBek9EZ3hPQT09>

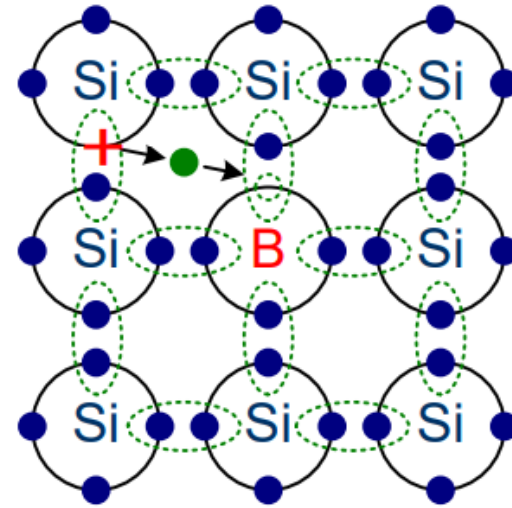
# Doping of Silicon Semiconductors

(a) n-type Doping



n-doping with phosphorus

(b) p-type Doping



p-doping with boron

<https://www.halbleiter.org/pdf/en/Fundamentals/Fundamentals%20-%20Doping.pdf>

# Doping of Silicon Semiconductors-Extrinsic



<https://www.youtube.com/watch?v=5ZNeDxfgYAE>

# Doping of Silicon Semiconductors-Extrinsic

1. Column V elements (P, As, Sb): “Donors”, concentration  $N_d$  [unit :  $\text{cm}^{-3}$ ]
2. Column III elements (B): “Acceptors”, concentration  $N_a$  [unit :  $\text{cm}^{-3}$ ]

At room temp almost all impurity atoms are ionized, so

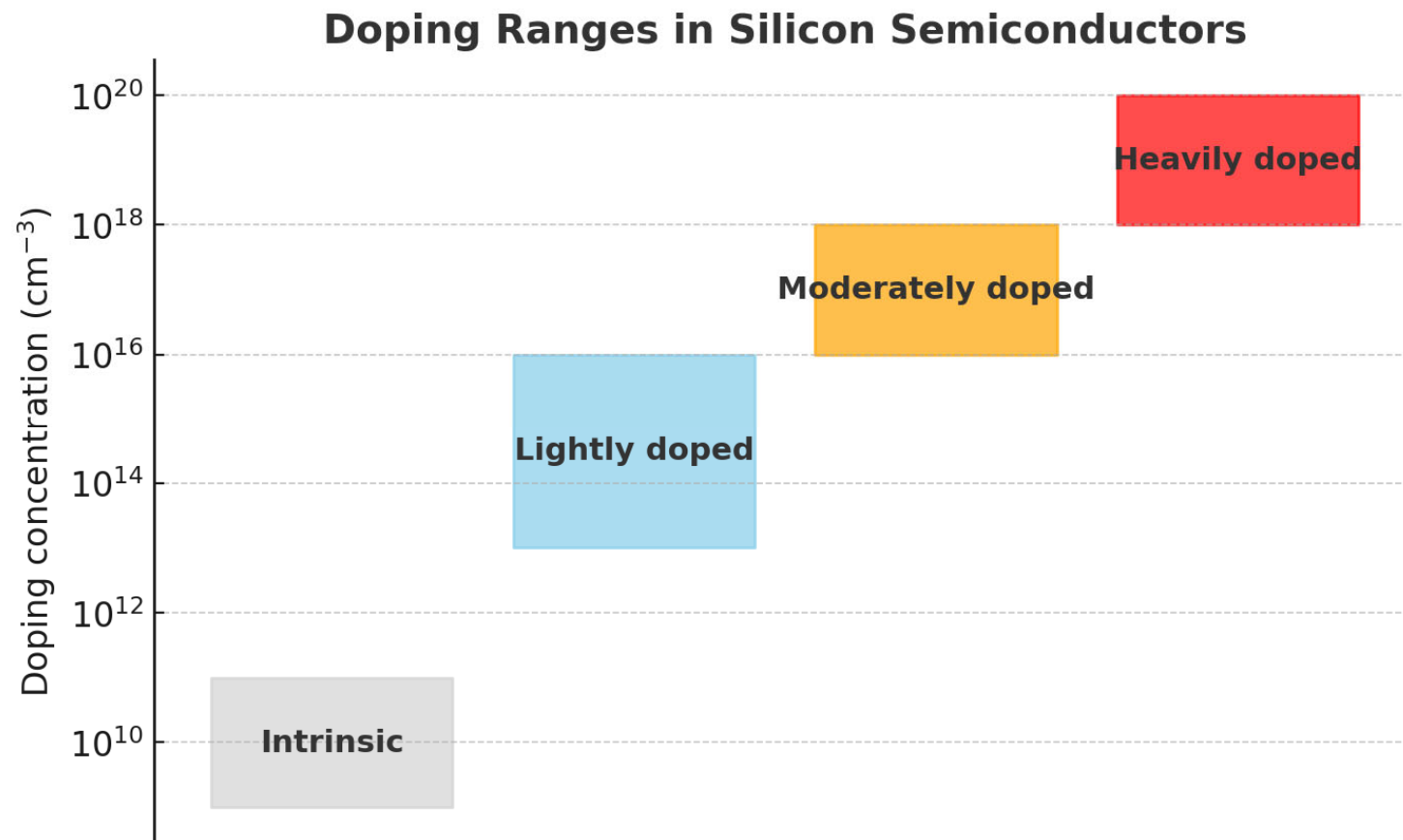
- $N_d^+ \approx N_d$
- $N_a^- \approx N_a$

Simplified expressions for  $n$  and  $p$  in terms of  $n_i$  and  $E_F$

$$\begin{aligned} n &= n_i e^{(E_F - E_i)/kT} \\ p &= n_i e^{(E_i - E_F)/kT} \end{aligned} \quad \Rightarrow \quad np = n_i^2$$



# Doping of Silicon Semiconductors-Extrinsic



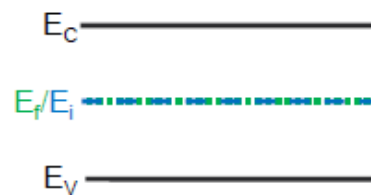
# Doping of Silicon Semiconductors-Extrinsic

## Comparative Summary

Property	Lightly Doped	Heavily Doped
Dopant concentration	$10^{13}-10^{16} \text{ cm}^{-3}$	$10^{18}-10^{20} \text{ cm}^{-3}$
Resistivity	High	Low
Depletion width	Wide	Narrow
Switching speed	Slower	Faster
Common usage	Drift/channel regions, detectors	Source/drain, emitter, ohmic contact

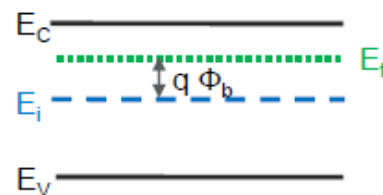
# Energy Bands

- $E_f$  = Fermi level
- $E_i$  = Intrinsic Fermi level
- $E_c$  = Conduction band edge
- $E_v$  = Valence band edge
- $E_g$  = Band gap



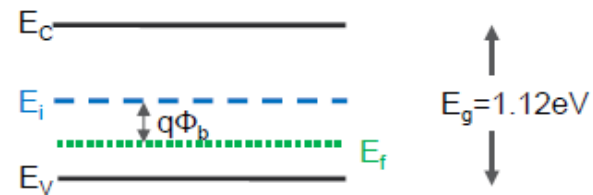
Undoped Si

$$n=p=n_i$$



N-Type Si

$$n \gg p$$



P-Type Si

$$n \ll p$$

$|E_f - E_i| = q \Phi_b$  is known as Fermi potential (bulk potential), measure the doping strength

$$\text{For Si, } n_i = 1.5 \times 10^{10} \text{ cm}^{-3} \quad n = n_i e^{\frac{(E_f - E_i)}{kT}} = n_i e^{\frac{q \Phi_b}{kT}} \quad p = n_i e^{\frac{(E_i - E_f)}{kT}} = n_i e^{\frac{q \Phi_b}{kT}}$$

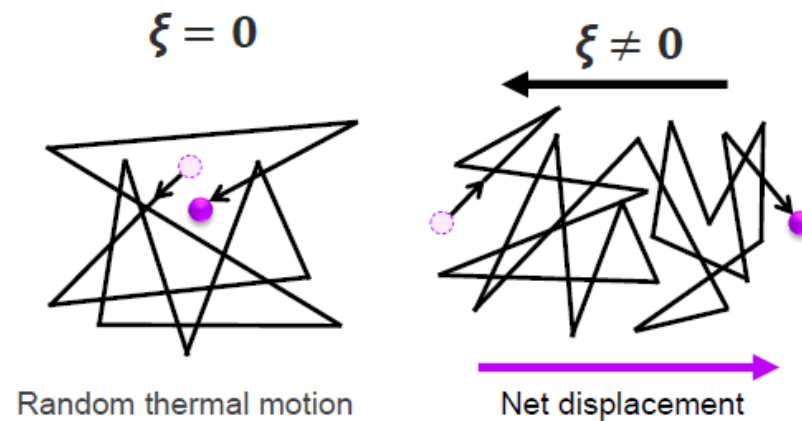
# Carrier Transport in Semiconductors

# Thermal Equilibrium in Semiconductors

- In a semiconductor, thermal equilibrium is a steady state where the temperature is uniform and constant (no temperature gradient)
- No external forces such as voltages, electrical field, magnetic field
- No net motion of charges and energy

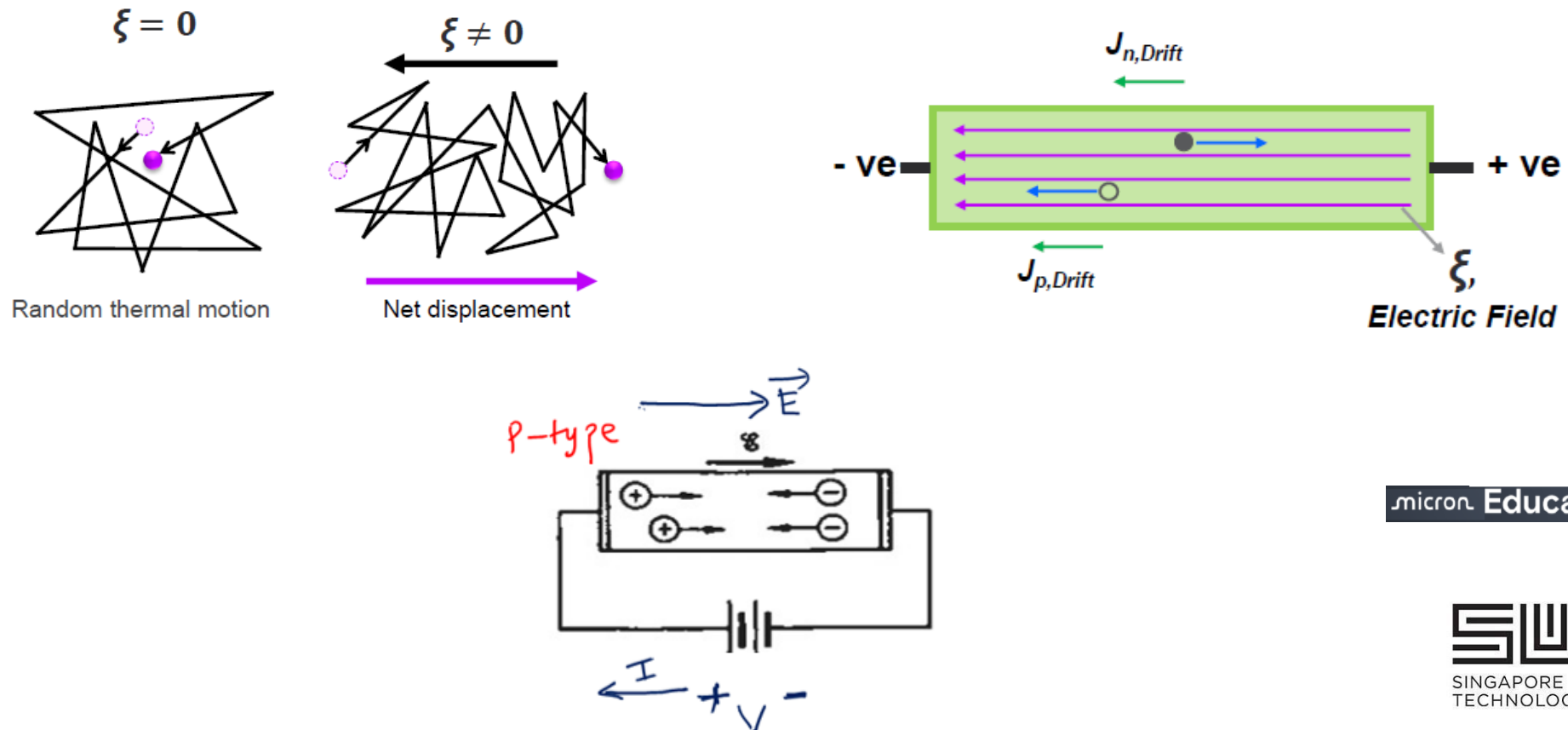
# Drift Current

Carrier drift in semiconductors is the directed movement of electrons and holes in response to an applied electric field, resulting in a net drift current



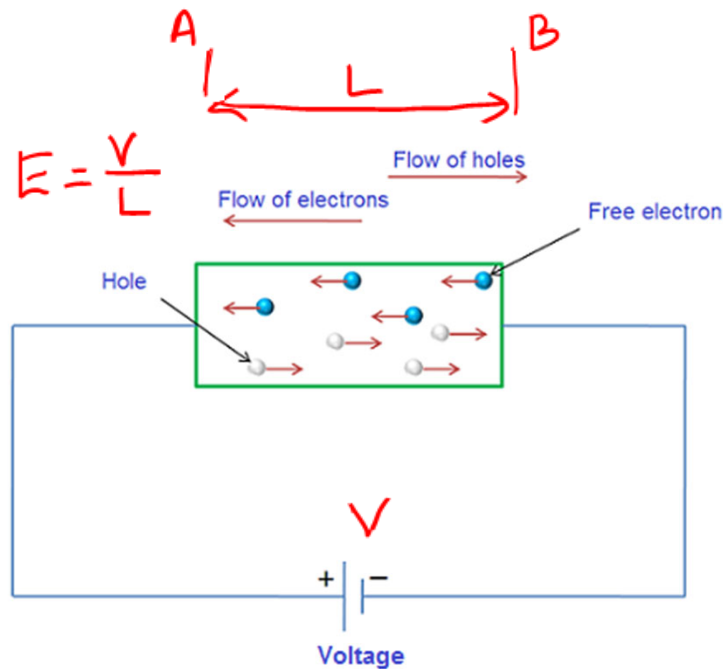
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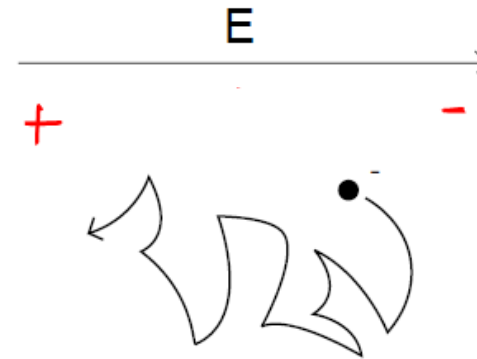
# Drift Current

Holes and electrons acquire an average net velocity, proportional to the electric field  $E$ .



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$$F = \pm qE$$

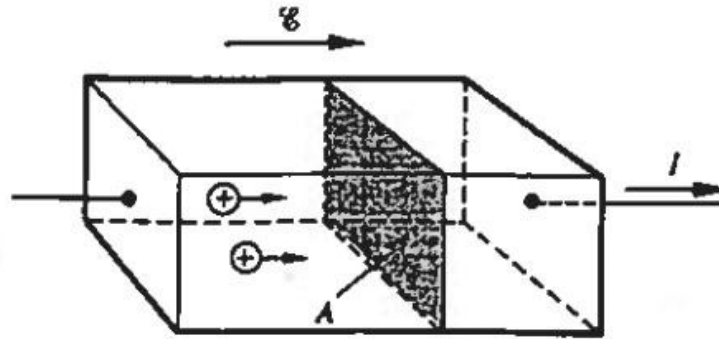


<https://www.physics-and-radio-electronics.com/electronic-devices-and-circuits/semiconductor/drift-current.html>



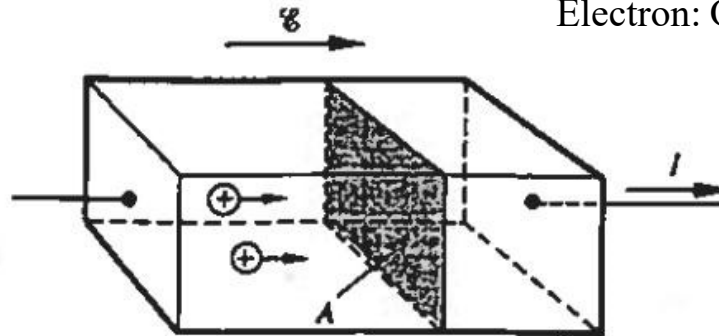
# Drift Current

Holes: Towards the direction of Field  
Electron: Opposite to the direction of Field



Expanded view of a biased *p*-type semiconductor bar of cross-sectional area *A*.

# Drift Current



Holes: Towards the direction of Field  
Electron: Opposite to the direction of Field

Expanded view of a biased *p*-type semiconductor bar of cross-sectional area *A*.

$$v_d t$$

... All holes this distance back from the  $v_d$ -normal plane will cross the plane in a time  $t$ .

$$v_d t A$$

... All holes in this volume will cross the plane in a time  $t$ .

$$p v_d t A$$

... Holes crossing the plane in a time  $t$ .

$$q p v_d t A$$

... Charge crossing the plane in a time  $t$ .

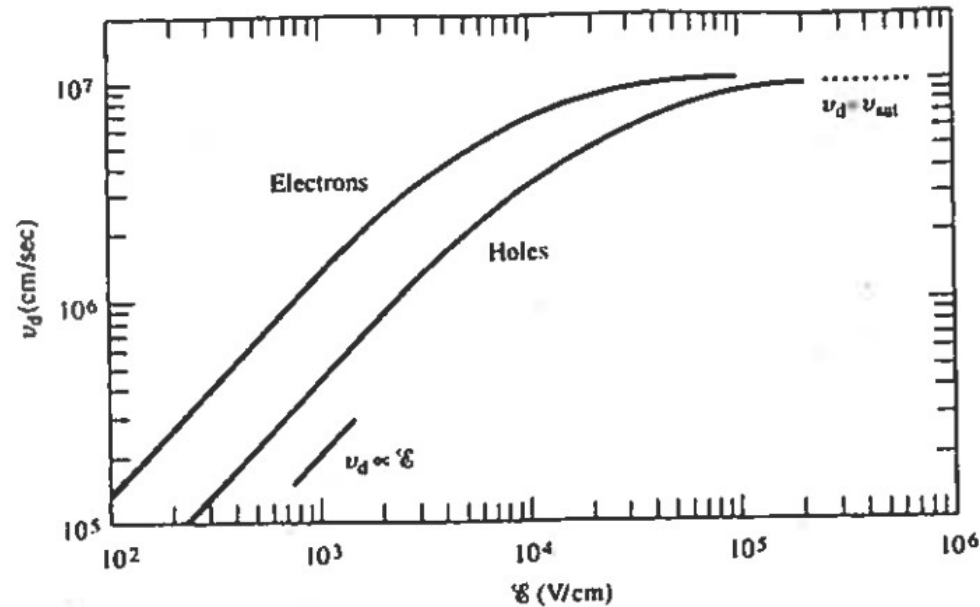
$$q p v_d A$$

... Charge crossing the plane per unit time.

$$I_{pdri ft} = q p v_d A$$

$$J_{p|drift} = q p v_d$$

# Carrier Mobility



Measured drift velocity of the carriers in ultrapure silicon maintained at room temperature as a function of the applied electric field. Constructed from the data fits and the data respectively in Jacoboni et al.<sup>[4]</sup> and Smith et al.<sup>[5]</sup>

$$v_d = \begin{cases} \mu_0 E & \dots E \rightarrow 0 \\ v_{sat} & \dots E \rightarrow \infty \end{cases}$$

- Mathematical Relation:

$$\mu = \frac{q\langle\tau\rangle}{m^*}$$

- $\langle\tau\rangle$ : Mean free time between collisions.
- $m^*$ : Effective mass of carriers.

# Carrier Mobility

- Units ( $\frac{cm^2}{Volt \cdot sec}$ )

Parameter	Silicon (Si)	Gallium Arsenide (GaAs)
Electron Mobility ( $\mu_n$ )	1360 cm <sup>2</sup> /V·s	8000 cm <sup>2</sup> /V·s
Hole Mobility ( $\mu_p$ )	460 cm <sup>2</sup> /V·s	400 cm <sup>2</sup> /V·s

Key Observation

$\mu_n > \mu_p$  for both Si and GaAs

- **Mathematical Relation:**

$$\mu = \frac{q\langle\tau\rangle}{m^*}$$

- $\langle\tau\rangle$ : Mean free time between collisions.
- $m^*$ : Effective mass of carriers.

# Mobility : Relationship to Scattering

**Definition of Mobility:** Measures ease of carrier motion in a crystal.

**Impact of Scattering:** Mobility decreases with increased motion-impeding collisions.

## Types of Scattering:

**Lattice Scattering:** Collisions with thermally agitated lattice atoms. (Phonon Scattering)



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- **Mathematical Relation:**

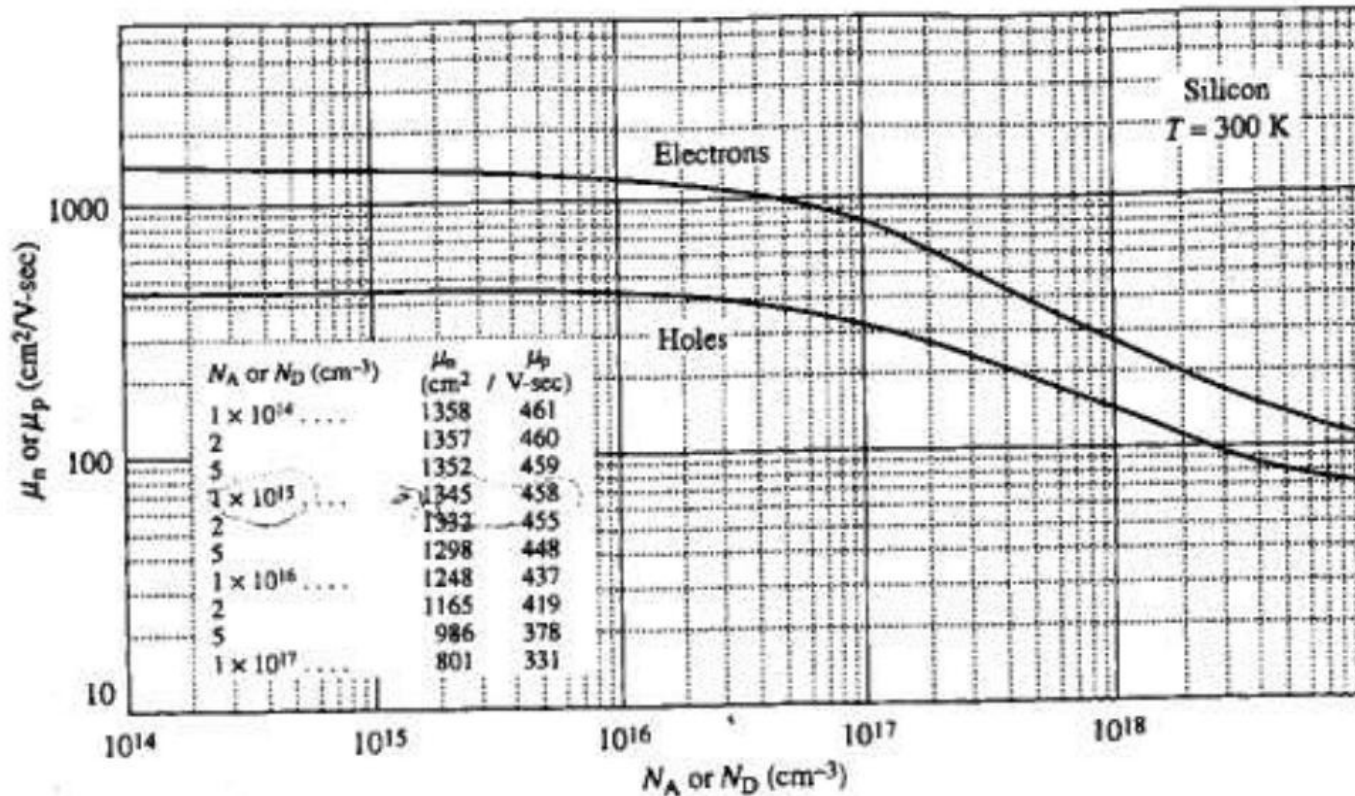
$$\mu = \frac{q\langle\tau\rangle}{m^*}$$

- $\langle\tau\rangle$ : Mean free time between collisions.
- $m^*$ : Effective mass of carriers.

**Mobility ( $\mu$ )** decreases as scattering increases.

**Mobility ( $\mu$ )** decreases as carrier effective mass increases. → Lighter carrier more readily

# Mobility : Doping Dependence



$$\mu = \frac{q\langle\tau\rangle}{m^*}$$

**Silicon**

Room Temperature



# Mobility : Doping Dependence

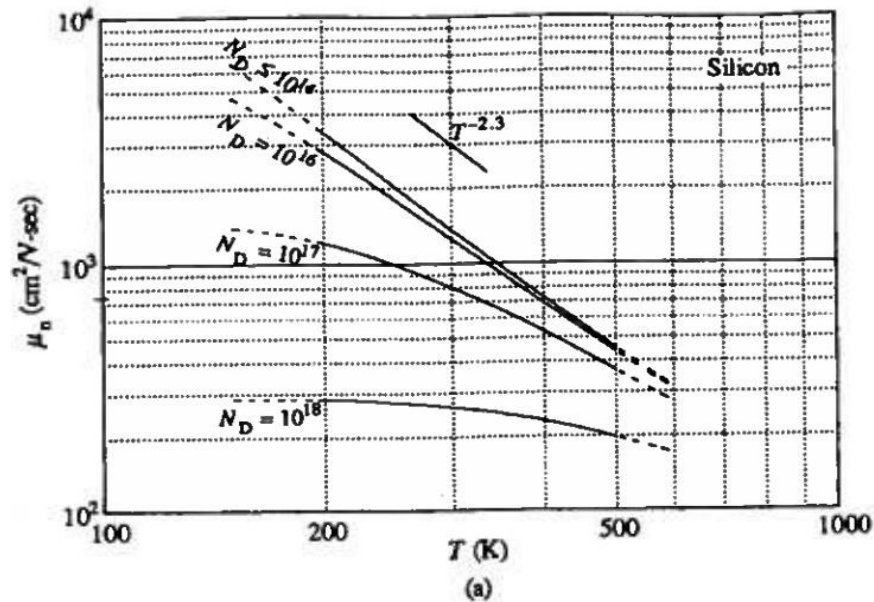
## •General Trend:

- Electron and hole mobilities in **semiconductors** show **doping dependence**.
- At **low doping** mobility is **independent** of doping.
- For **high doping**, mobility **decreases with increasing doping concentration**.

## Key Takeaway:

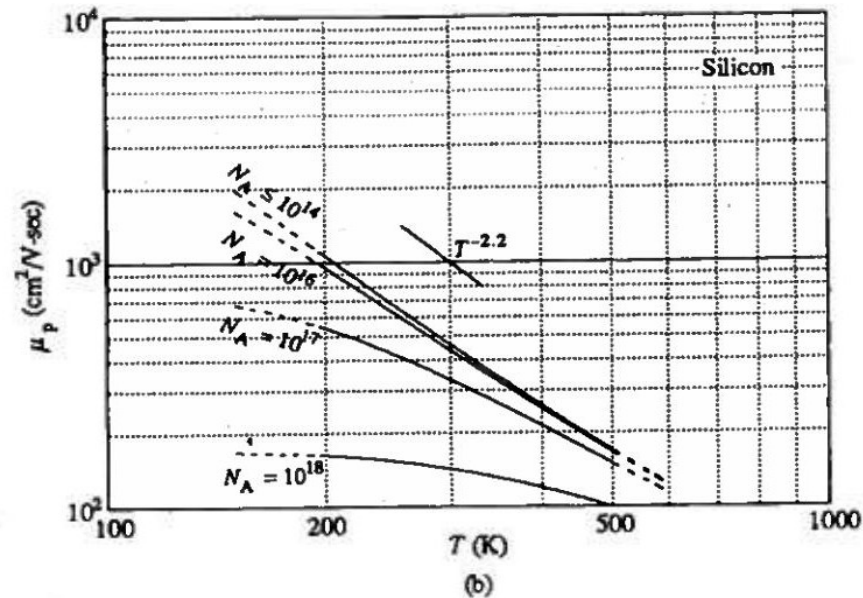
- **Higher doping reduces mobility** due to **increased scattering centers** (acceptors/donors).
- This trade-off is crucial in semiconductor **device design** and **performance optimization**.

# Mobility : Temperature Dependence (electrons)



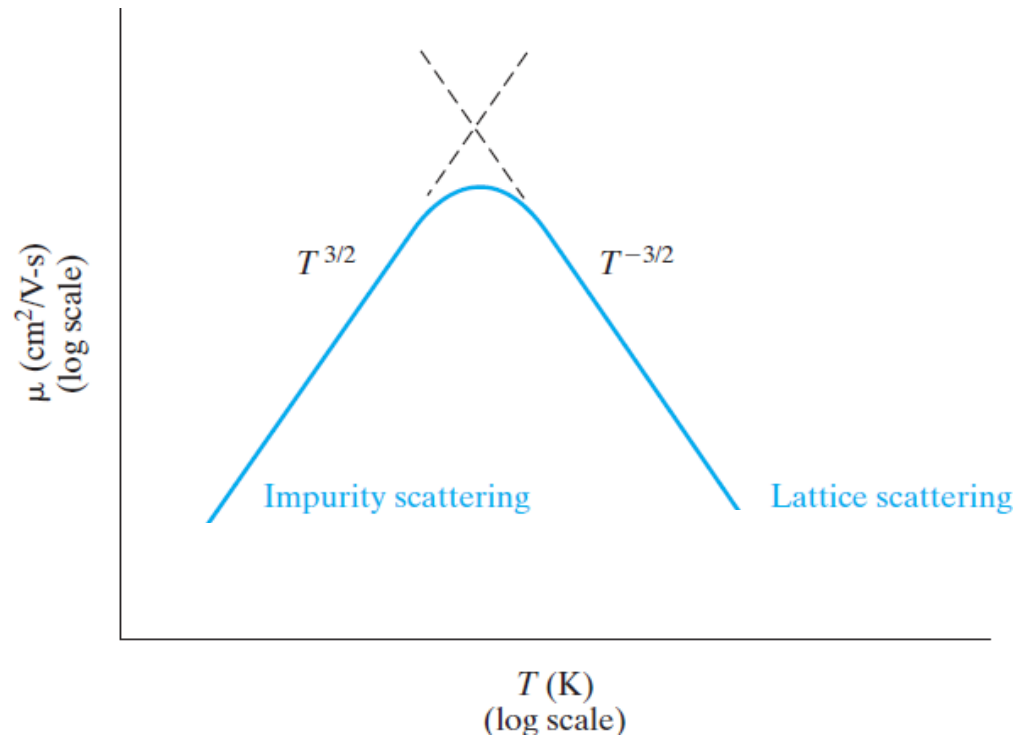
Temperature dependence of (a) electron and (b) hole mobilities in silicon for dopings ranging from  $\leq 10^{14}/\text{cm}^3$  to  $10^{18}/\text{cm}^3$ . The curves were constructed using the empirical fit relationships and parameters presented in Exercise 3.1. The dashed line portion of the curves correspond to a slight extension of the fit beyond the verified  $200 \text{ K} \leq T \leq 500 \text{ K}$  range of validity.

# Mobility : Temperature Dependence (Holes)



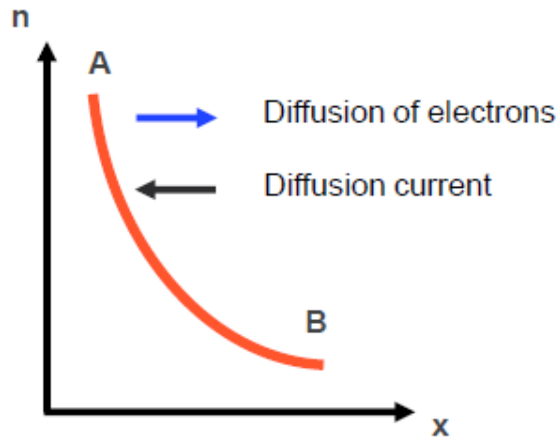
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# Mobility : Temperature Dependence

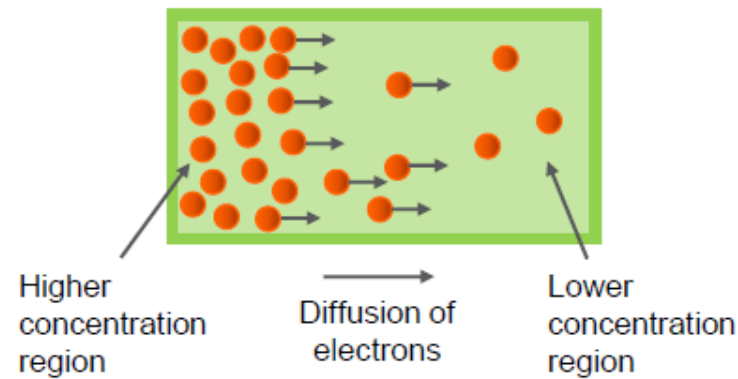


# Diffusion Current

Electric current due to **concentration gradients of carriers**



N type



$$J_{n,Diff} \propto \frac{dn}{dx}$$

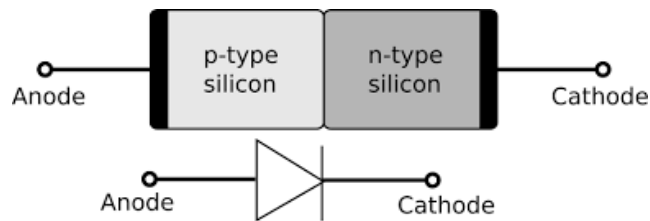
$$J_{n,Diff} = eD_n \frac{dn}{dx}$$

$D_n$  : Diffusion coefficient

# PN Junction diodes

# P-N Junction (Diode)

A p-n junction diode is a basic semiconductor device that controls the flow of electric current in a circuit. It has a positive (p) side and a negative (n) side created by adding impurities to each side of a silicon semiconductor.

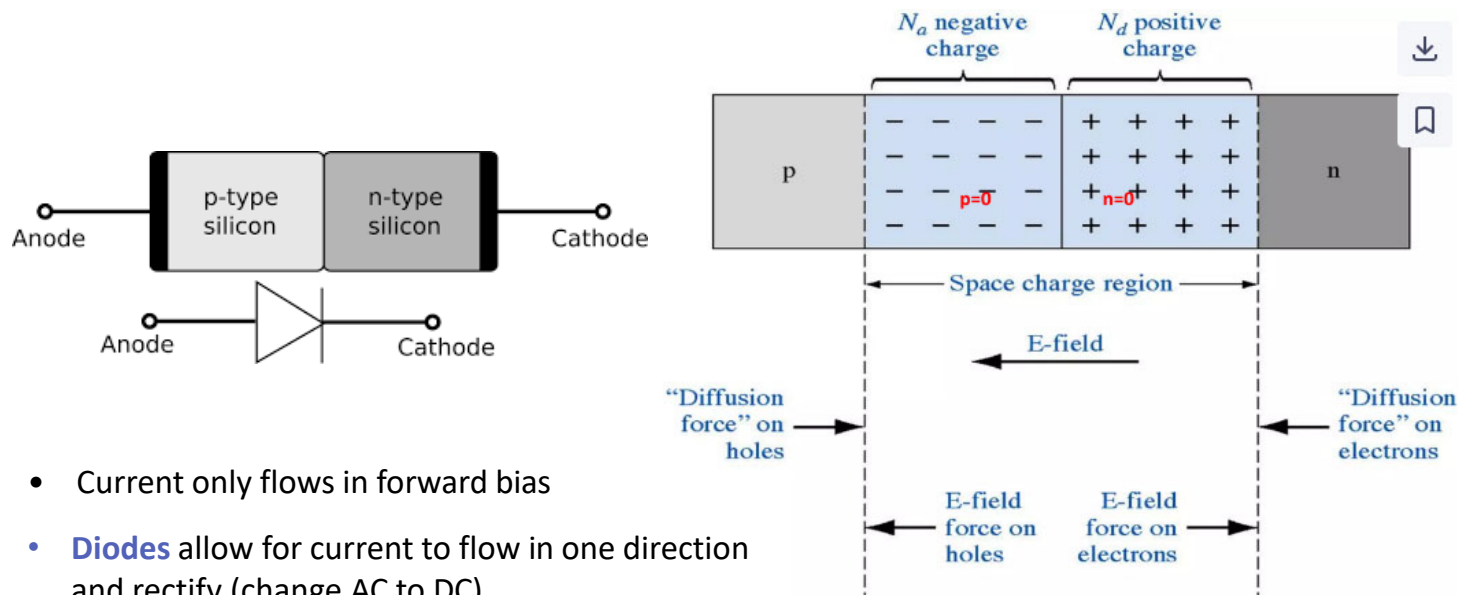


- Current only flows in forward bias
- **Diodes** allow for current to flow in one direction and rectify (change AC to DC)

<https://www.slideshare.net/slideshow/p-n-junctioneema/68227503>

# P-N Junction (Diode)

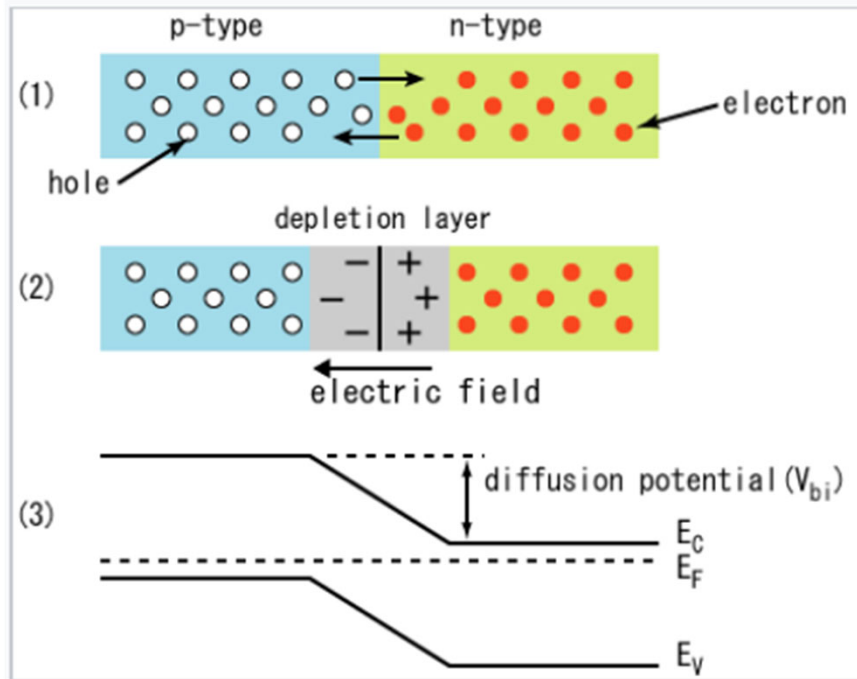
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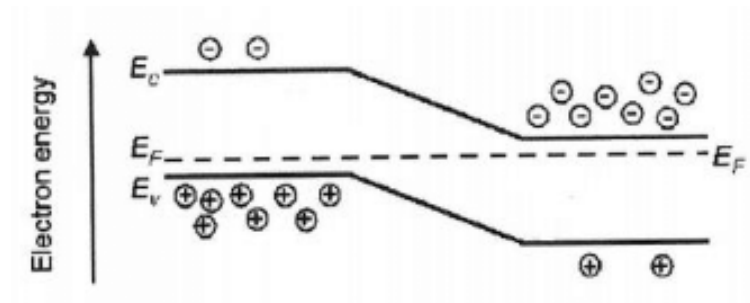
<https://www.slideshare.net/slideshow/p-n-junctioneema/68227503>



# P-N Junction (Diode)-Built in potential

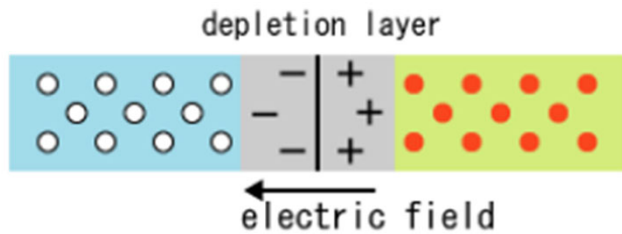


The built-in potential of a P-N junction is the potential difference that develops at the intersection of its p-type semiconductor material and n-type semiconductor material. This built-in potential develops in the depletion region.

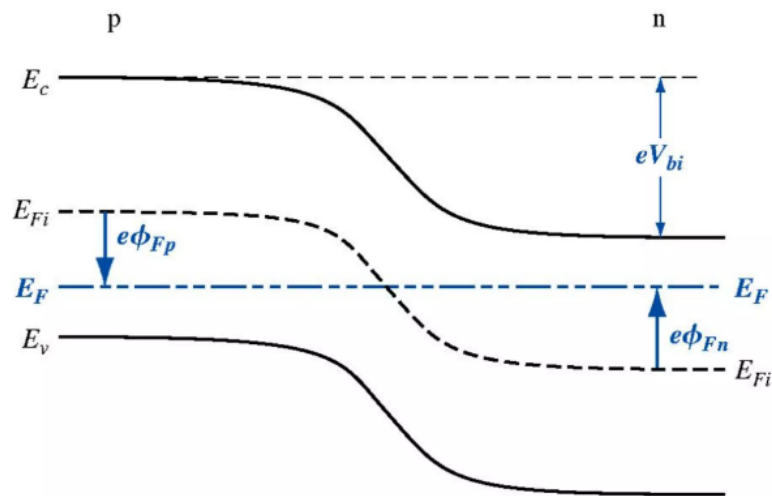


<https://study.com/academy/lesson/p-n-junction-diode-definition-properties.html>

# P-N Junction (Diode)-Built in potential



The built-in potential of a P-N junction is the potential difference that develops at the intersection of its p-type semiconductor material and n-type semiconductor material. This built-in potential develops in the depletion region.



$$\phi_{bi} = \frac{kT}{q} \ln \frac{N_d N_a}{n_i^2}$$

## Formula

### PN Junction Built-in Potential

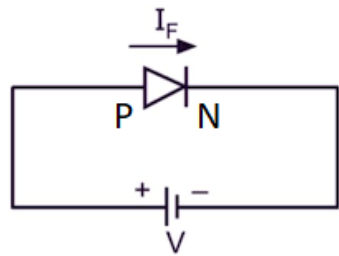
$$V_{\text{built-in}} = \frac{kT}{q} \ln \left( \frac{N_D N_A}{n_i^2} \right)$$

$V_{\text{built-in}}$	→ Built-in potential in volts
$N_D$	→ n type - donor atoms concentration
$N_A$	→ p type - acceptor atoms concentration
$n$	→ concentration of electrons
$kT/q$	→ thermal voltage
$T$	→ temperature in Kelvin
$q$	→ charges in coulombs

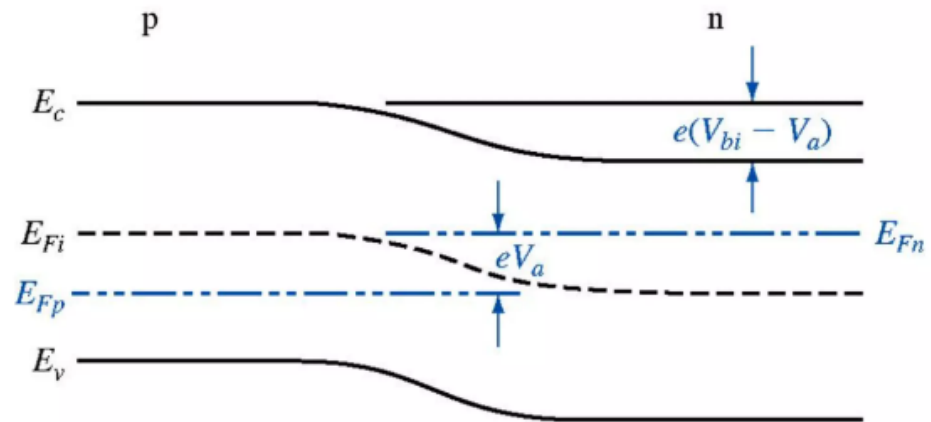
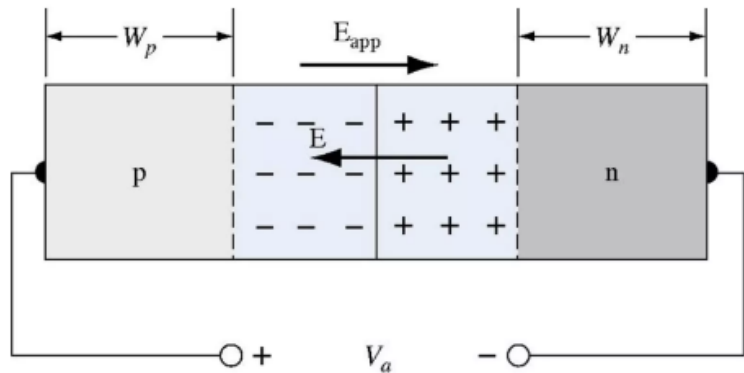
getcalc.com

# P-N Junction (Diode)-Forward Bias

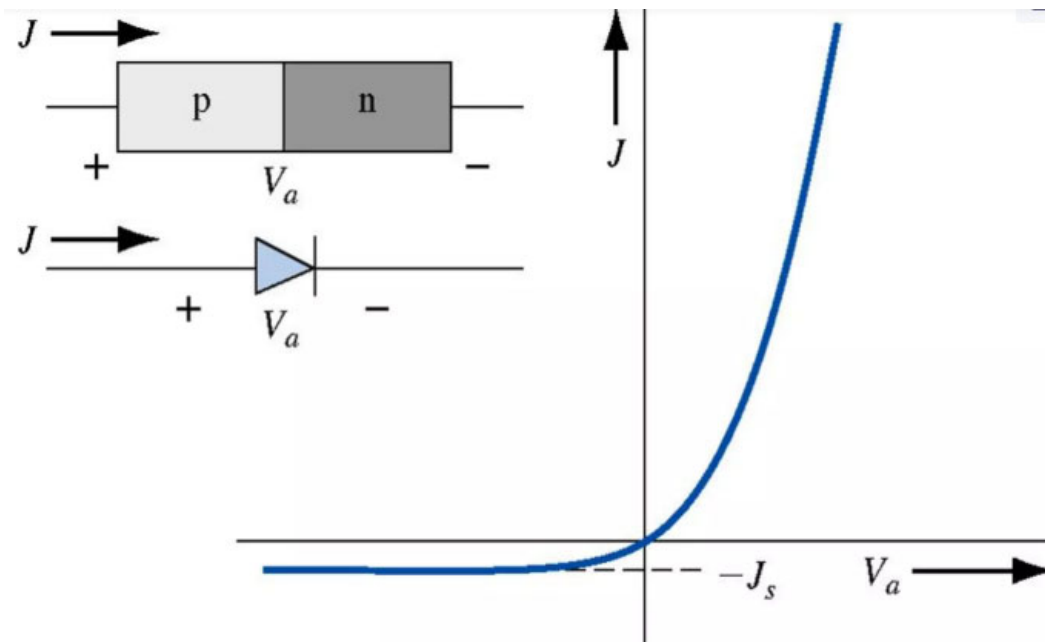
When positive terminal of the source is connected to the P side and the negative terminal is connected to N side then the junction diode is said to be connected in forward bias condition.



**FORWARD BIAS PN JUNCTION**

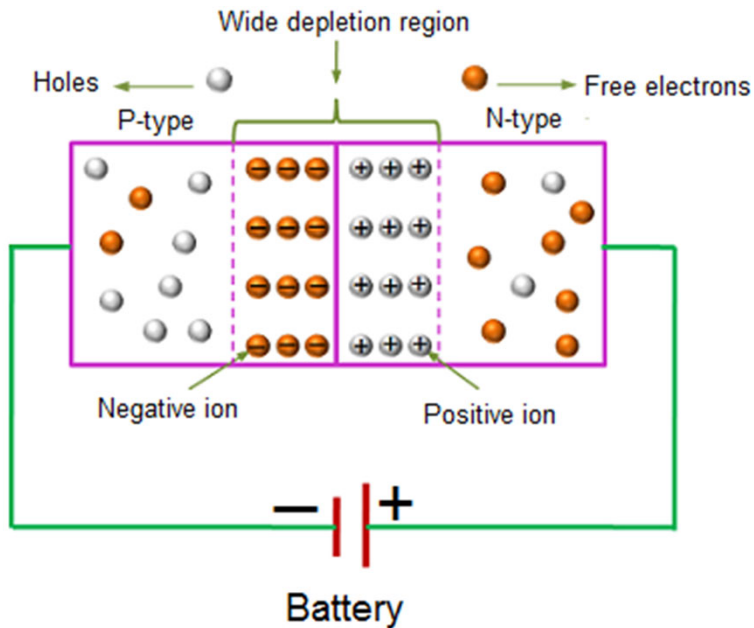


## P-N Junction (Diode)-Forward Bias



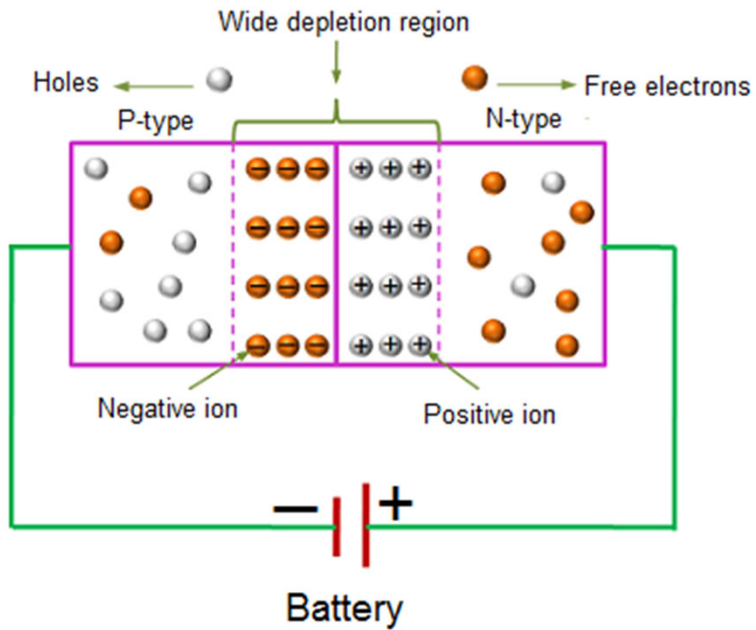
$$J \approx J_s \left[ \exp\left(\frac{eV_a}{kT}\right) - 1 \right]$$

# P-N Junction (Diode)-Reverse Bias

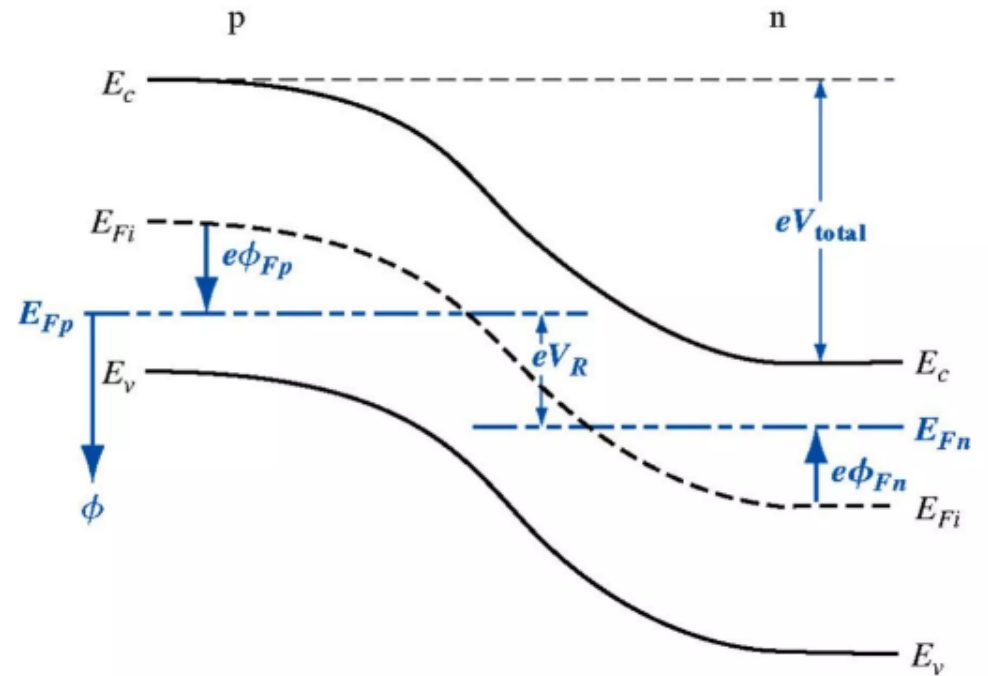


- Positive terminal attracts the electrons away from the junction in N side and negative terminal attracts the holes away from the junction in P side.
- As a result of it, the width of the potential barrier increases that impedes the flow of majority carriers in N side and P side.

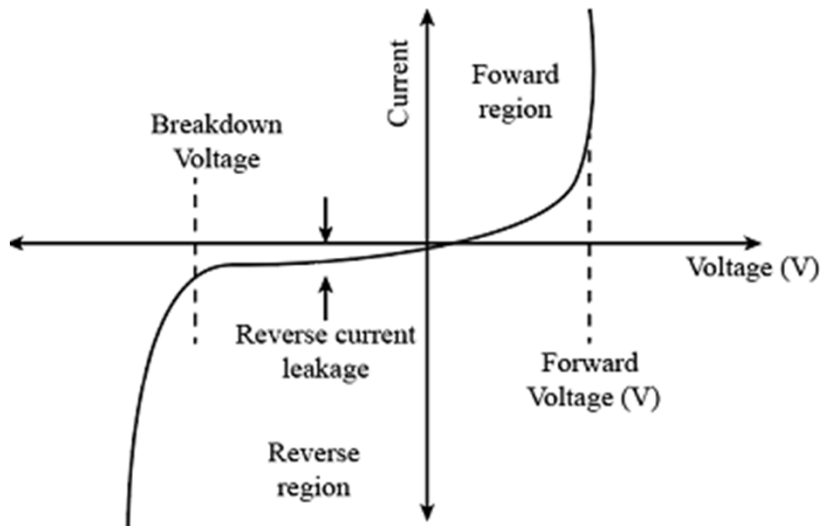
# P-N Junction (Diode)-Reverse Bias



**BAND diagram of REVERSE BIAS PN JUNCTION**



# P-N Junction (Diode)-Reverse Bias

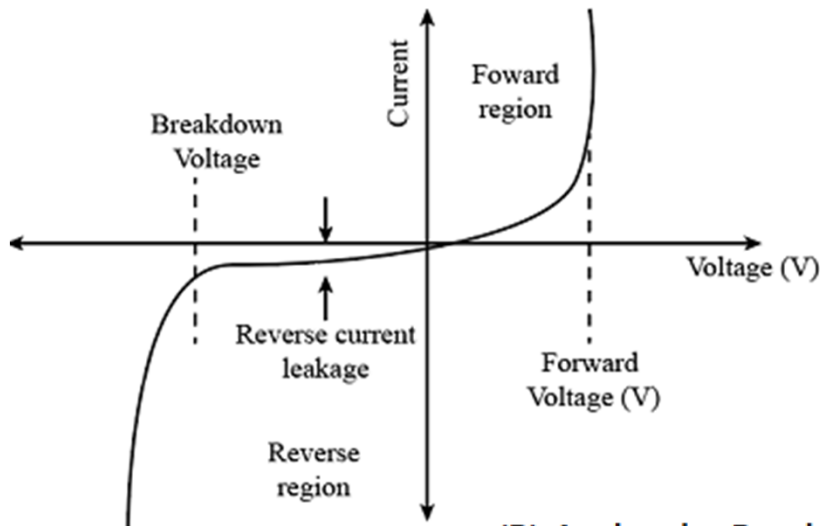


**Breakdown occurs by two mechanisms.**

## (A) Zener Breakdown (Low Reverse Voltage, $< \sim 5\text{--}6\text{ V}$ )

- Occurs in **heavily doped PN junctions** (narrow depletion region).
- Strong **electric field** develops across the narrow depletion layer.
- This field is strong enough to **break covalent bonds** and cause **quantum mechanical tunneling** of electrons from the valence band (P-side) into the conduction band (N-side).
- Result  $\rightarrow$  sudden increase in current.
- Dominant in **low-voltage Zener diodes**.

# P-N Junction (Diode)-Reverse Bias



**Breakdown occurs by two mechanisms.**

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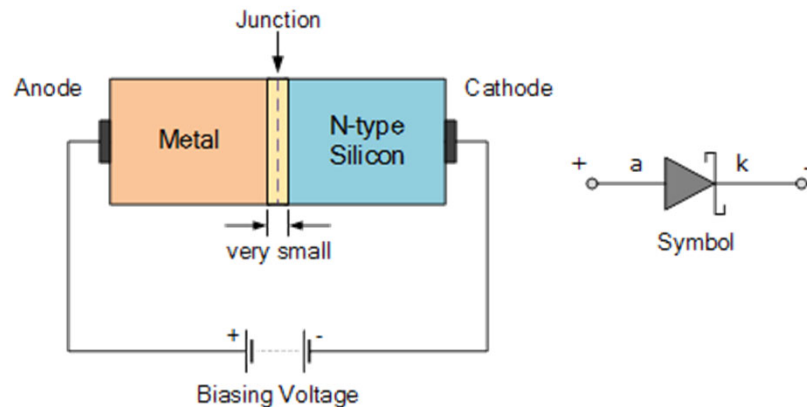
## (B) Avalanche Breakdown (Higher Reverse Voltage, $> \sim 6\text{ V}$ )

- Occurs in **lightly doped PN junctions** (wide depletion region).
- Minority carriers (electrons/holes) accelerated by the strong electric field gain enough energy to **ionize atoms** when they collide with the lattice.
- This generates **new electron-hole pairs**, which are again accelerated  $\rightarrow$  **chain reaction (avalanche multiplication)**.
- Result  $\rightarrow$  sharp rise in current.
- Dominant in **power diodes and high-voltage junctions**.



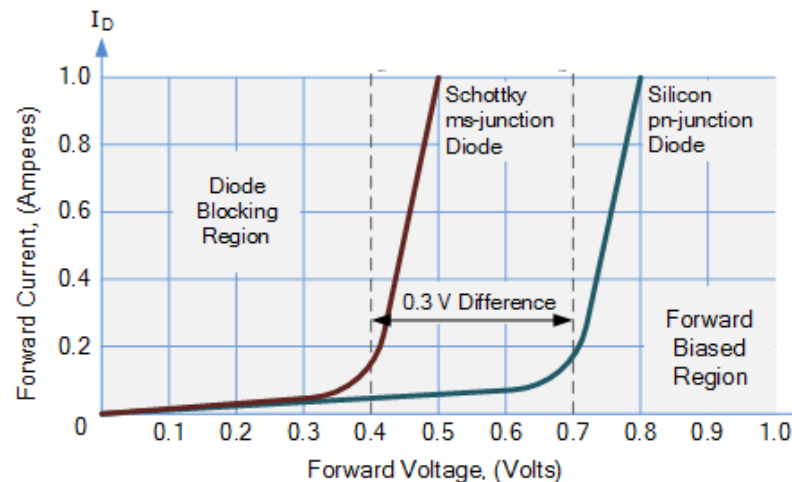
# Schottky Diode: Metal-Semiconductor Junction

- The Schottky diode is a semiconductor diode formed by the junction of a semiconductor (N-type) with a metal.
- Current conduction is mainly due to **majority carriers** (usually electrons from the N-type side).
- It has a low forward voltage drop and a very fast switching action.
- The most common contact metal used for Schottky diode construction is “Silicide” which is a highly conductive silicon and metal compound.



<https://www.electronics-tutorials.ws/diode/schottky-diode.html>

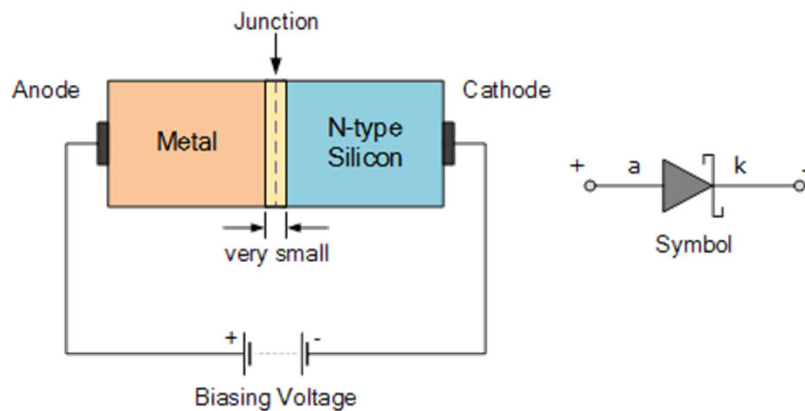
Schottky Diode IV-Characteristics



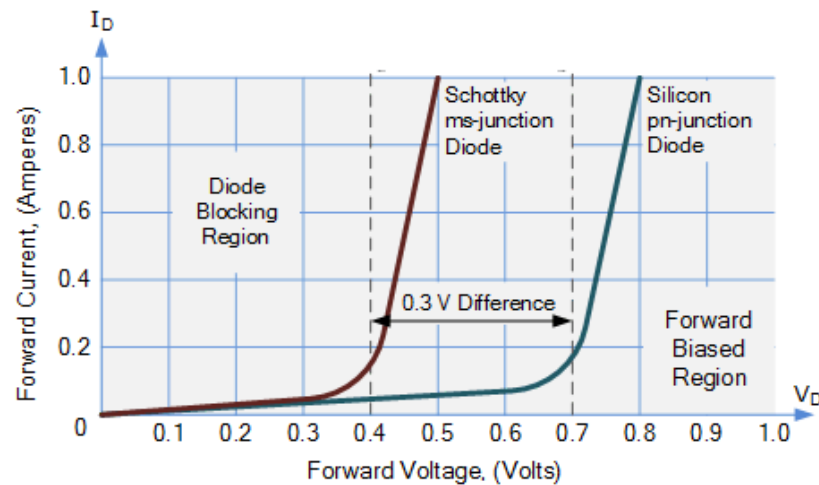
# Schottky Diode: Metal-Semiconductor Junction

## Barrier Potential

- **PN Diode:** Has a barrier potential of about **0.7 V (Si)**.
- **Schottky Diode:** Has a much lower barrier potential, typically **0.2–0.3 V**, because it is a metal–semiconductor junction.



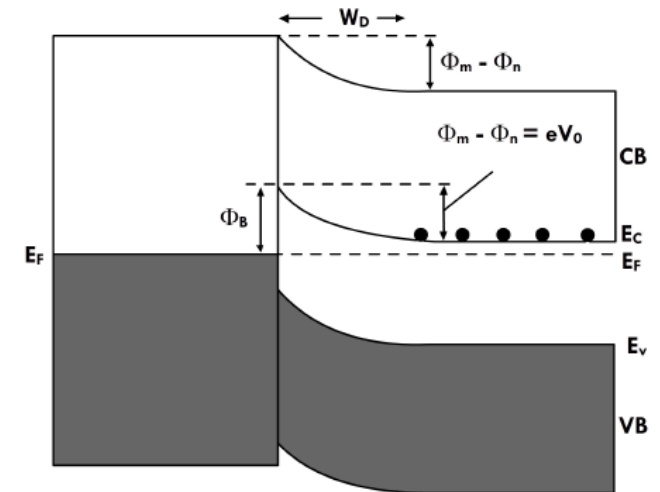
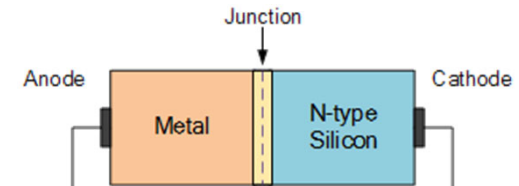
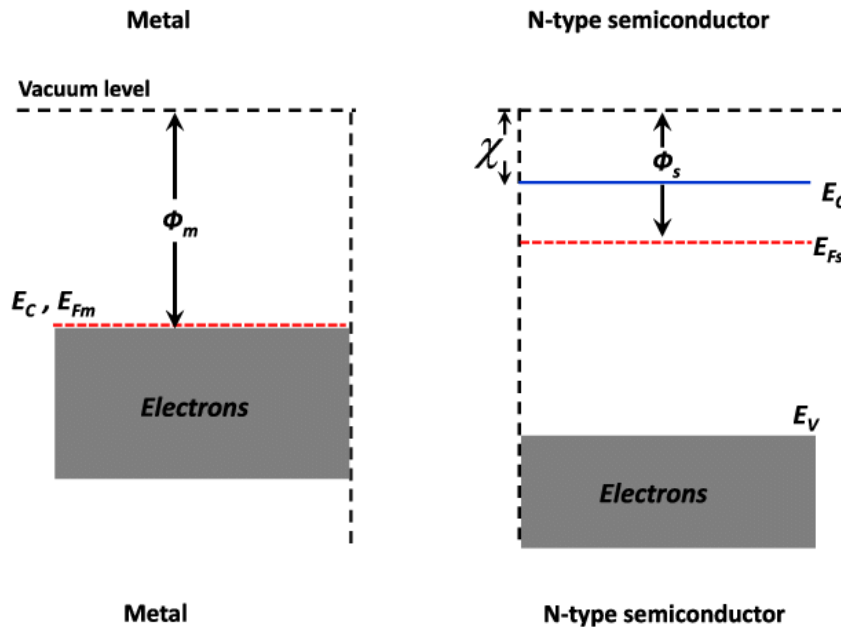
Schottky Diode IV-Characteristics



<https://www.electronics-tutorials.ws/diode/schottky-diode.html>

# Schottky Diode: Metal-Semiconductor Junction

- A Schottky junction is formed when the semiconductor has a lower work function than the metal.

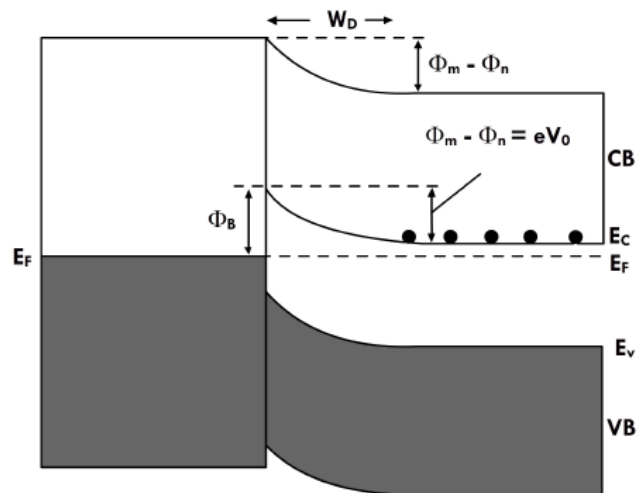
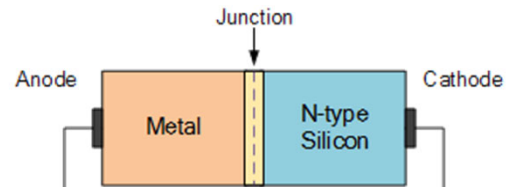


**Equilibrium condition**

<https://www.electronics-tutorials.ws/diode/schottky-diode.html>

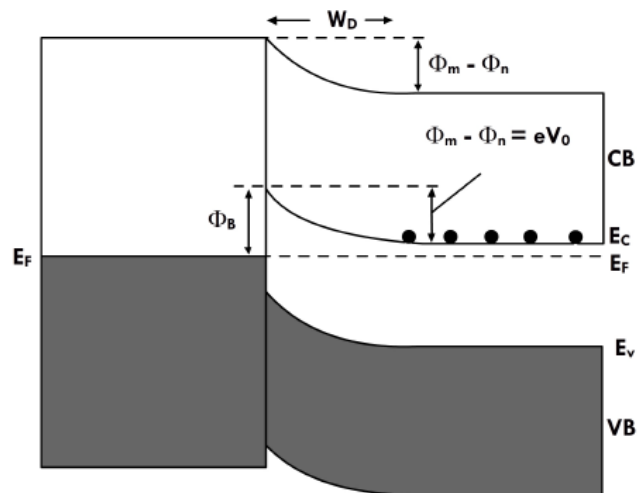
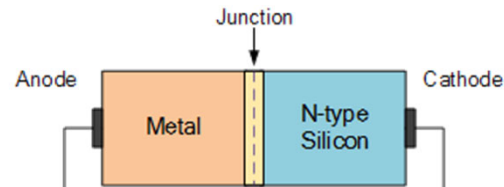
<https://www.icrfq.net/schottky-diode/>

# Schottky Diode: Metal-Semiconductor Junction

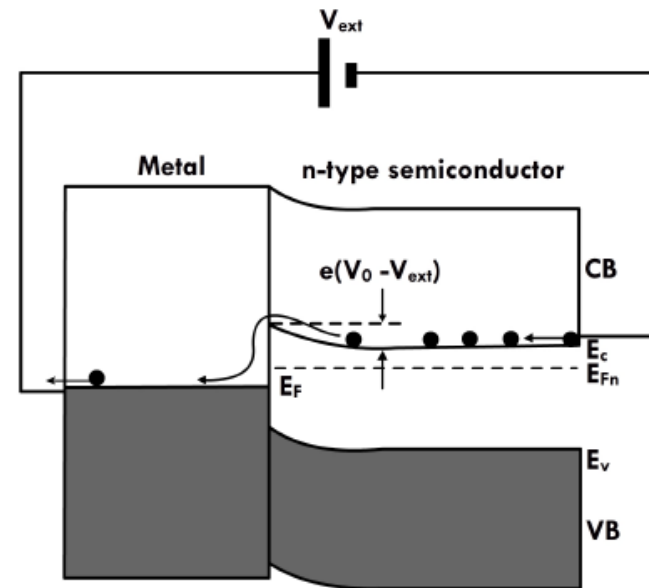


**Equilibrium condition**

# Schottky Diode: Metal-Semiconductor Junction (Forward Bias)

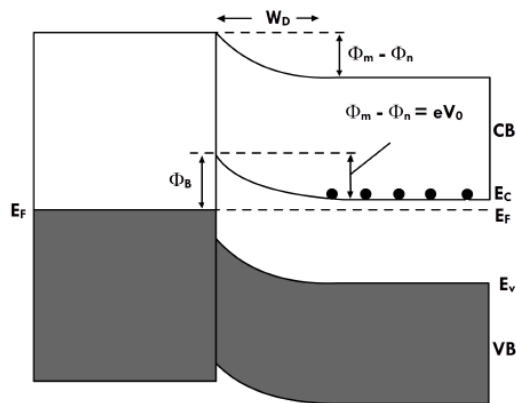
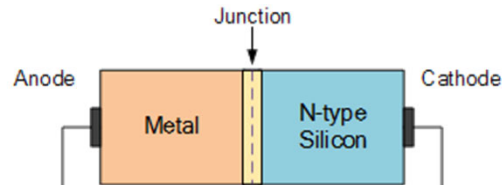


Equilibrium condition

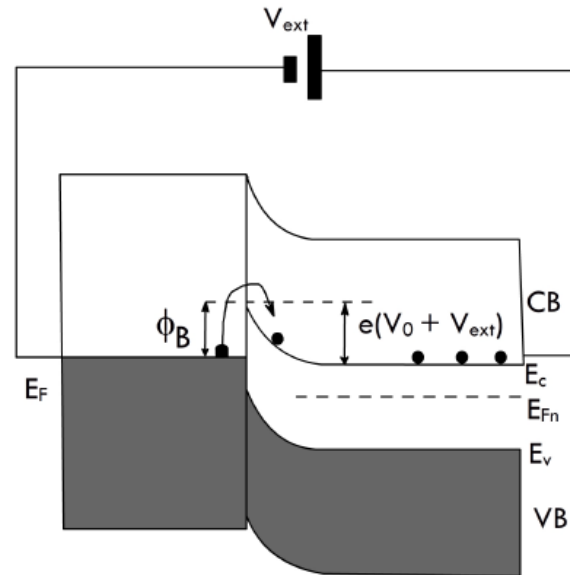


Forward Bias

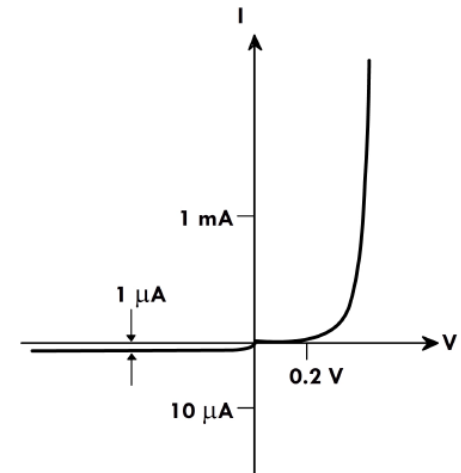
# Schottky Diode: Metal-Semiconductor Junction (Reverse Bias)



Equilibrium condition



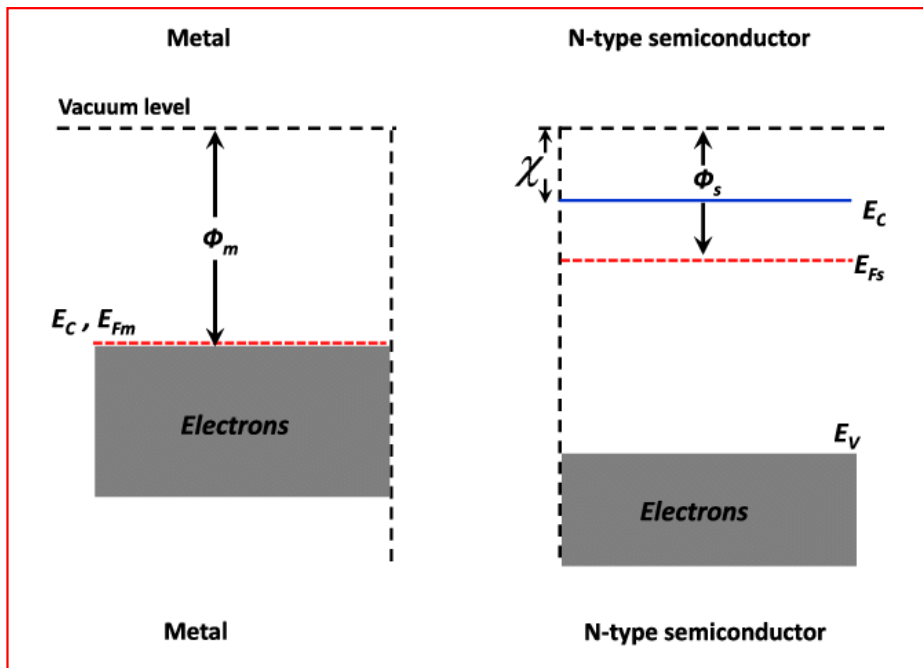
Reverse Bias



# Ohmic Contact

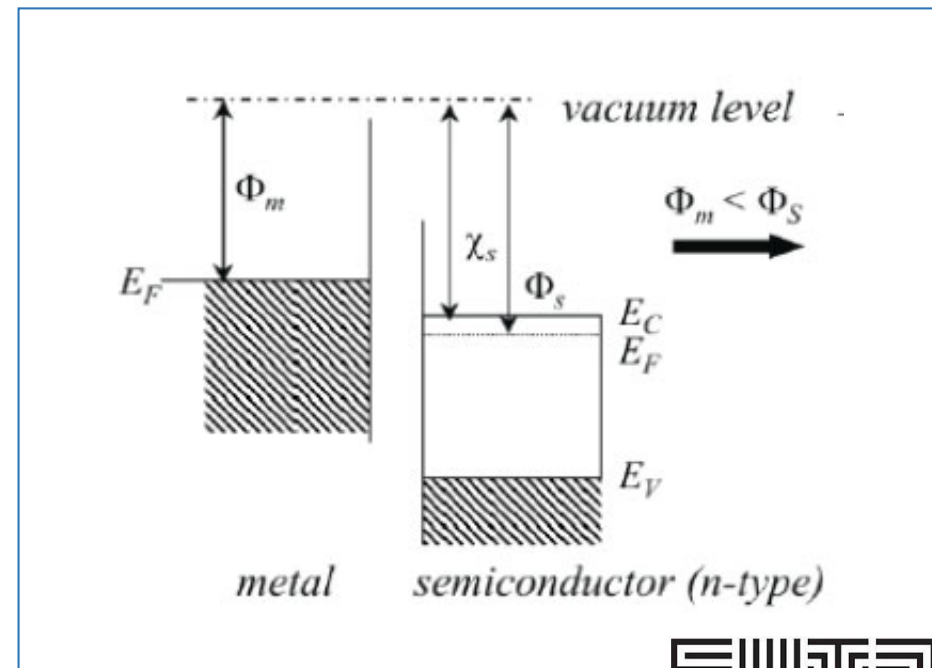
- A Schottky junction is formed when the semiconductor has a lower work function than the metal. When the semiconductor has a higher work function the junction formed is called the Ohmic junction.

Schottky junction



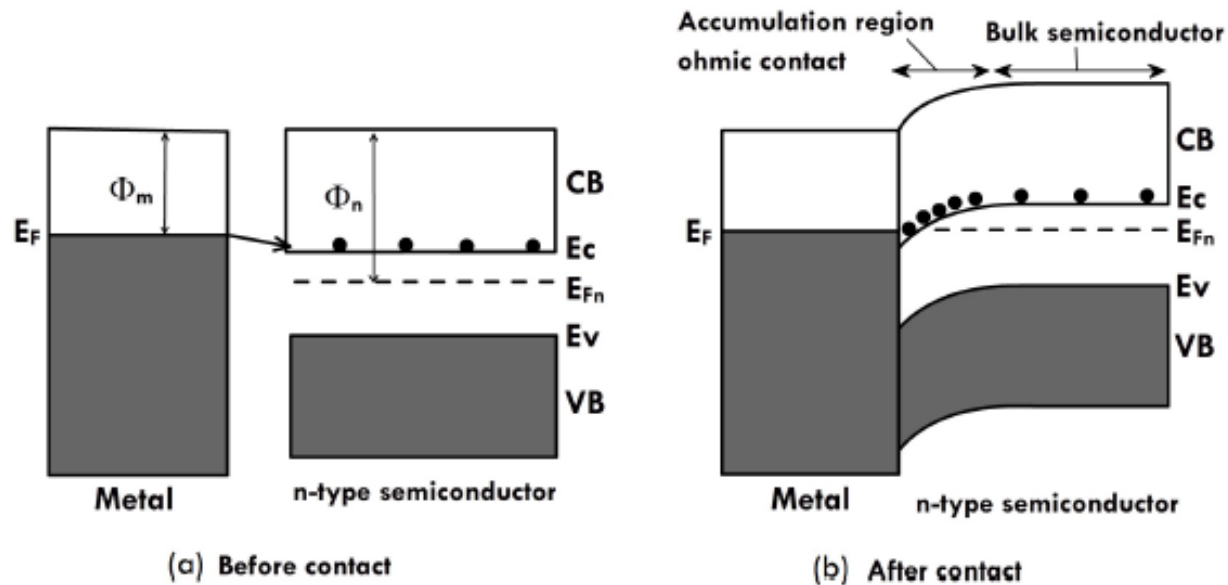
<https://www.icrfq.net/schottky-diode/>

Ohmic junction



# Ohmic Contact

- A Schottky junction is formed when the semiconductor has a lower work function than the metal. When the semiconductor has a higher work function the junction formed is called the Ohmic junction.
- Ohmic junction behaves as a resistor conducting in both forward and reverse bias. The resistivity is determined by the bulk resistivity of the semiconductor.

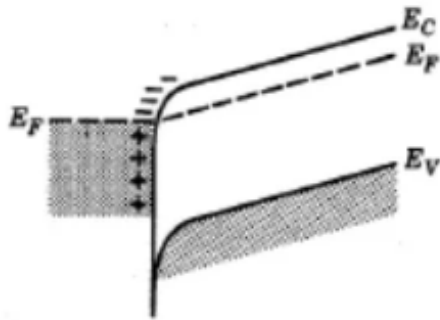


Ohmic Contact

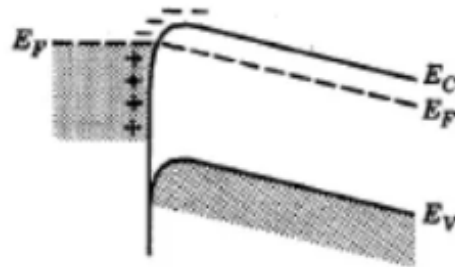


# Ohmic Contact (Forward bias and Reverse Bias)

Forward Bias ( $V_A > 0V$ )



Reverse Bias ( $V_A < 0V$ )



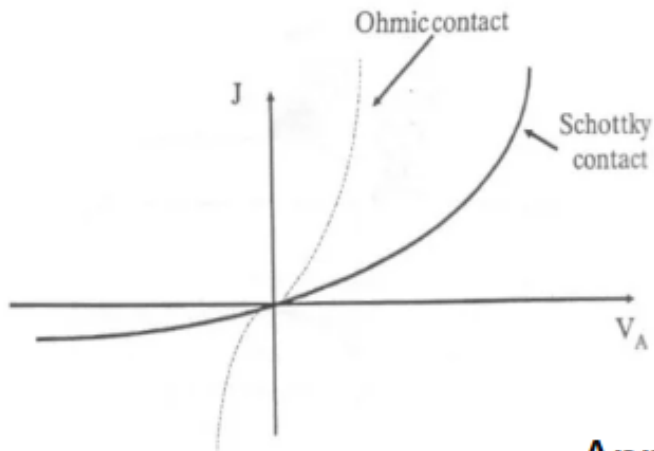
**Heavy doping near the junction** (degenerate semiconductor):  
High doping narrows the depletion region, enabling **tunneling** of carriers  
→ ohmic behavior even if a barrier exists.

- When bias is applied, practically all applied voltage drops across the higher resistance region which is the bulk neutral semiconductor.
- Current is therefore determined by the resistance of the bulk, ie. measures property of device

- no depletion region
- **accumulation of majority carriers** near the semiconductor surface
- low resistance to current flow
- non-rectifying □ ohmic

# Ohmic Contact (Forward bias and Reverse Bias)

## Current-Voltage Characteristics



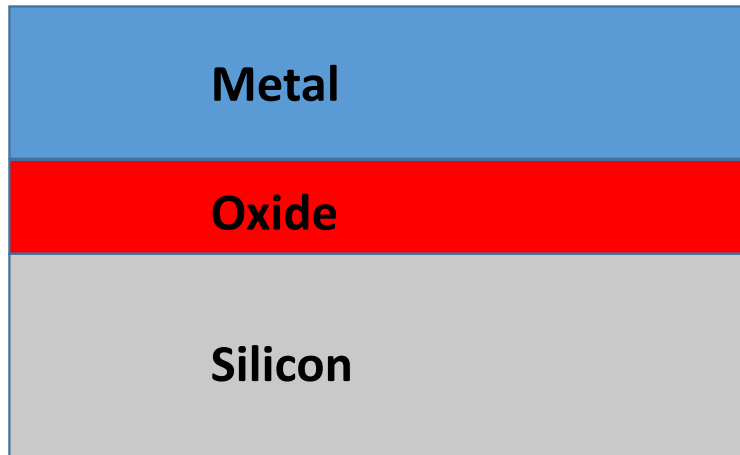
## Some discussions:

- Ohmic contacts have large current in both directions
- Typically, the resistance is very small
- Since the contact resistance is very small, the voltage will be dropped on the semiconductor

## Applications

- Ohmic contacts are essential in **all semiconductor devices** (diodes, transistors, ICs).
- They provide the **electrical connection between metal electrodes and the semiconductor regions** (e.g., source, drain, emitter, collector).
- Without ohmic contacts, devices would behave like diodes at their terminals instead of allowing proper current injection.

# MOS structures



- Accumulation mode
- Depletion mode
- Inversion mode

# MOS Capacitor

- MOS: Metal-oxide-semiconductor
  - Gate: metal (or polysilicon)
  - Oxide: silicon dioxide, grown on substrate
- MOS capacitor: two-terminal MOS structure

